

**IN THE CLAIMS**

This listing of claims replaces all prior versions, and listings, in this application.

This listing of claims replaces all prior versions, and listings, in this application.

1. (original) A viscosity reducible radiation curable composition comprising at least one radiation curable component and a filler, wherein the composition has the properties:

- i) a yield stress value of < 1100 Pa,
- ii) a viscosity (at a shear rate of  $1 \text{ sec}^{-1}$ ) between 1 and 1500 Pa.sec, and
- iii) a filler settling speed less than 0.3 mm/day.

2. (original) A viscosity reducible radiation curable composition comprising at least one radiation curable component and a filler, wherein the composition has the properties:

- i) a yield stress value of < 1100 Pa,
- ii) a viscosity (at a shear rate of  $10 \text{ sec}^{-1}$ ) between 1 and 200 Pa.sec, and
- iii) a filler settling speed less than 0.3 mm/day.

3. (previously presented) The radiation curable composition according to claim 1, wherein the yield stress value is < 500 Pa.

4. (previously presented) The radiation curable composition according to claim 1, wherein the composition comprises at least one photoinitiator.

5. (previously presented) The radiation curable composition according to claim 1, wherein the composition has a thixotropic index of at least 3.

6. (previously presented) The radiation curable composition according to claim 1, wherein the composition contains a thixotropic agent.

7. (original) The radiation curable composition according to claim 6, wherein the thixotropic agent is selected from the group consisting of Thixcin R, Thixatrol 1, Thixatrol GST, Thixatrol ST, Aluminum stearate 132 and 22, MPA 14, Ken react LICA 38 and KR 55.

8. (original) The radiation curable composition according to claim 6, wherein the thixotropic agent is selected from the group consisting of Thixcin R, Thixatrol 1, Thixatrol GST, and Thixatrol ST.

9. (previously presented) The radiation curable composition according to claim 1, wherein the composition comprises a flow aid.

10. (currently amended) The radiation curable composition according to claim 9, wherein the flow agent aid is selected from the group consisting of polyacrylates and polyalkyleneoxide modified polydimethylsiloxane.

11. (currently amended) The radiation curable composition according to claim 9, wherein the flow agent aid comprises Modaflow 2100.

12. (previously presented) The radiation curable composition according to claim 1, wherein the composition retrieves the viscosity after a steady shear of 1 second within 300 seconds.

13. (previously presented) The radiation curable composition according to claim 1, wherein the composition comprises cationically curable components, and radically curable components.

14. (original) The radiation curable composition according to claim 9, wherein the composition comprises between 30 and 90 wt% of cationically curable components.

15. (previously presented) The radiation curable composition according to claim 1, wherein the composition comprises between 5 and 50 wt% of radically polymerizable components.

16. (currently amended) A viscosity reducible radiation curable composition comprising

5-70 wt% of a difunctional epoxy compound ;

0.1-15 wt% of an acrylate having a functionality of larger than 2 ;

0.1-10 wt% of a thixotropic agent ;

0.01-5 wt% of a flow modifier aid ;

10-90 wt% of a filler ; and

at least one photoinitiator .

17. (original) The composition according to claim 16, wherein the composition has the properties:

- i) a yield stress value of < 1000 Pa,
- ii) a viscosity (at a shear rate of 1 sec<sup>-1</sup>) between 0 and 1500 Pa.sec, and
- iii) a filler settling speed less than 0.3 mm/day.

18. (withdrawn) A method for forming a three dimensional object comprising the steps of:

- a) coating a layer of a viscosity reduced composition as define in claim 1 on a surface;
- b) allowing said layer to become a viscosity reducible composition layer having a viscosity greater than said viscosity reduced layer;
- c) exposing said viscosity reducible layer to radiation imagewise by radiation means in order to photoform said layer imagewise;
- d) repeating steps a) through c) until the three dimensional object is being formed.

19. (new) The radiation curable composition according to claim 9, wherein the flow aid comprises ethyl acrylate-2-ethylhexyl acrylate copolymer.

20. (new) The viscosity reducible radiation curable composition of claim 16 wherein said flow aid comprises an ethyl acrylate-2-ethylhexyl acrylate copolymer.

21. (New) The composition according to claim 16, wherein the difunctional epoxy compound is selected from the group consisting bisphenol A diglycidyl ether, bisphenol F diglycidyl ether, hydrogenated bisphenol A diglycidyl ether, hydrogenated bisphenol F diglycidyl ether, 3,4-epoxycyclohexylmethyl-3',4'-epoxycyclohexane

carboxylate, bis(3,4-epoxycyclohexylmethyl)adipate, 1,4-butanediol diglycidyl ether, 1,6-hexanediol diglycidyl ether, polyethylene glycol diglycidyl ether, and polypropylene glycol diglycidyl ether.

22. (New) The composition according to claim 16, wherein the acrylate having a functionality of larger than 2 is selected from the group consisting of trimethylolpropane tri(meth)acrylate, ethylene oxide-modified trimethylolpropane tri(meth)acrylate, dipentaerythritol hexa(meth)acrylate, dipentaerythritol penta(meth)acrylate, and ditrimethylolpropane tetra(meth)acrylate

23. (New) The composition according to claim 16, wherein the thixotropic agent is selected from the group consisting of polyvinylpyrrolidone, titanate coupling agents, aluminum distearate, aluminium tristearate, copolymers with acidic groups, fumed silica, organic derivatives of castor oil and polyoxyethylene-polyoxypropylene block copolymers.

24. (New) The composition according to claim 16, wherein said composition further comprises one or more selected from photosensitizer consisting of amine compounds; photosensitizers consisting of tioxanethone, derivatives of thioxanethone, anthraquinone, derivatives of antraquinone, anthracene, derivatives of anthracene, perylene, derivatives of perylene, benzophenone, benzoin isopropyl ether; reactive diluents; resins such as epoxy resin, polyamide, polyamideimide, polyurethane, polybutadiene, polychloroprene, polyether, polyester, styrene/butadiene styrene block copolymer, petroleum resin, xylene resin, ketone resin, cellulose resin, fluorine containing oligomer, and silicon containing oligomer; polymerization inhibitors; polymerization initiation assistants; levelling agents; wettability improvers; surfactants; plasticizers; UV absorbers; silane coupling agents; resin particles; pigments; and dyes.